TOSHIBA Photocoupler GaAlAs Ired + Photo IC

TLP751

Digital Logic Ground Isolation
Line Receiver
Microprocessor System Interfaces
Switching Power Supply Feedback Control
Analog Signal Isolation

The TOSHIBA TLP751 consists of GaAlAs high—output light emitting diode and a high speed detector of one chip photo diode—transistor. This unit is 8—lead DIP.

TLP751 has internal base connection. This base pin should be used for analog application or enable operation. If base pin is open, output signal will be noisy by environmental condition. For this case, TLP750 is suitable.

- Switching speed: $t_{pHL} = 0.3 \mu s$ (typ.) $t_{pLH} = 0.5 \mu s$ (typ.)($R_L = 1.9 k\Omega$)
- TTL compatible
- UL recognized: UL1577, file no. E67349
- BSI approved: BS EN60065: 2002,

Certificate no. 8869 BS EN60950-1: 2002, Certificate no. 8870

- Isolation voltage: 5000Vrms(min.)
- Option(D4)type

VDE approved: DIN EN 60747-5-2,

Certificate no. 40009302

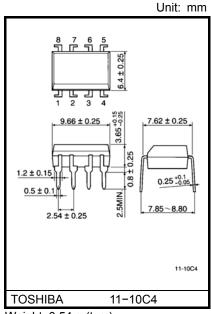
Maximum operating insulation voltage: 890 VpK Highest permissible over voltage: 8000 VpK

(Note) When a EN 60747-5-2 approved type is needed, please designate the "Option(D4)"

• Creepage distance: 6.4mm (min)

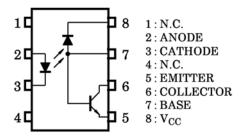
Clearance: 6.4mm (min)

Insulation thickness: 0.4mm (min)

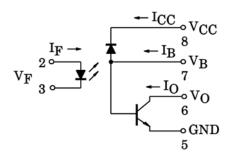


Weight: 0.54 g (typ.)

Pin Configuration(top view)



Schematic



Absolute Maximum Ratings (Ta = 25°C)

	Characteristic		Symbol	Rating	Unit
LED	Forward current	(Note 1)	l _F	25	mA
	Pulse forward current	(Note 2)	I _{FP}	50	mA
	Peak transient forward current	(Note 3)	I _{FPT}	1	А
	Reverse voltage		V _R	5	V
	Diode power dissipation	(Note 4)	P _D	45	mW
	Output current		Io	8	mA
Detector	Peak output current		l _{OP}	16	mA
	Output voltage		Vo	-0.5~15	V
	Supply voltage		V _{CC}	-0.5~15	V
	Base current		Ι _Β	5	mA
	Output power dissipation	(Note 5)	Po	100	mW
	Emitter-base reverse voltage		V _{EB}	5	V
Оре	Operating temperature range		T _{opr}	-55~100	°C
Sto	Storage temperature range		T _{stg}	-55~125	°C
Lea	Lead solder temperature(10s) (Note		T _{sol}	260	°C
Isol (AC	Isolation voltage (AC,1min.,R.H.≤ 60%) (Note 7		BVS	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- (Note 1) Derate 0.8mA above 70°C
- (Note 2) 50% duty cycle,1ms pulse width.

 Derate 1.6mA / °C above 70°C
- (Note 3) Pulse width $\leq 1\mu s$,300pps.
- (Note 4) Derate 0.9mW / °C above 70°C
- (Note 5) Derate 2mW / °C above 70°C
- (Note 6) Soldering portion of lead: up to 2mm from the body of the device.
- (Note 7) Device considered a two terminal device: Pins 1,2,3 and 4 shorted together and pins 5,6,7 and 8 shorted together.

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Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min.	Тур.	Max.	Unit	
LED	Forward voltage	V_{F}	I _F = 16 mA	_	1.65	1.85	V	
	Forward voltage Temperature coefficient	ΔV _F / ΔTa	I _F = 16 mA	_	-2	_	mV / °C	
	Reverse current	I_{R}	V _R = 5 V	_	_	10	μΑ	
	Capacitance between terminal	СТ	V _F = 0, f = 1 MHz	1	45	_	pF	
Detector	High level output current	I _{OH (1)}	$I_F = 0 \text{ mA}, V_{CC} = V_O = 5.5 \text{ V}$	_	3	500	nA	
		I _{OH} (2)	I _F = 0 mA, V _{CC} = V _O = 15 V	_	_	5		
		Іон	I _F = 0 mA, V _{CC} = V _O = 15 V	_	_	50	μΑ	
			Ta = 70°C					
	High level supply voltage	ICCH	I _F = 0 mA, V _{CC} = 15 V	1	0.01	1	μΑ	
	Current transfer ratio	I _O / I _F	I _F = 16 mA, V _{CC} = 4.5 V	10	30	_	%	
			V _O = 0.4 V	10				
Coupled	Low level output voltage	V _{OL}	I _F = 16 mA, V _{CC} = 4.5 V		_	0.4	V	
			I _O = 1.1 mA	_				
	resistance(input-output)	R _S	R.H. ≤ 60%, V _S = 500 V _{DC} (Note7)	1×10 ¹²	10 ¹⁴		Ω	
	Capacitance (input-output)	C _S	$V_S = 0, f = 1 \text{ MHz}$ (Note7)	_	0.8	_	pF	

Switching Characteristics (Ta = 25°C, V_{CC} = 5V)

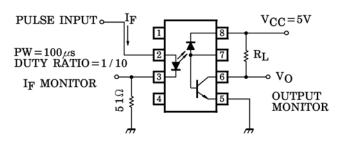
Characteristic		Symbol	Test Cir- cuit	Test Condition	Min.	Тур.	Max.	Unit
Propagation delay time (H→L)		t _{pHL}	1	$I_F = 0$ →16mA, $V_{CC} = 5V$, $R_L = 4.1 \text{ kΩ}$	_	0.2	_	μs
Propagation delay time (L→H)		t _{pLH}		I_F = 16→0mA V_{CC} = 5V, R_L = 4.1 kΩ	_	1.0	_	μs
Common mode transient immunity at logic high output	(Note 8)	CM _H		$I_F = 0 \text{ mA}, V_{CM} = 200 V_{p-p}$ $R_L = 4.1 \text{ k}\Omega$	_	400		V / µs
Common mode transient immunity at logic low output	(Note 8)	CML	2	I_F =16 mA V_{CM} = 200 V_{p-p} R_L = 4.1 kΩ	_	-1000	_	V / µs

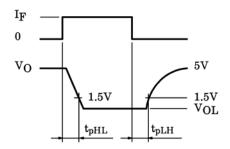
(Note 8) CM_L is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic low state($V_Q < 0.8V$).

 CM_H is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic high state($V_O > 2.0V$).

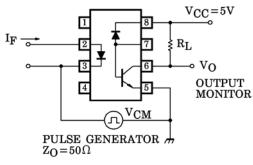
(Note 9) Maximum electrostatic discharge voltage for any pins: 100V (C = 200pF, R = 0).

Test Circuit 1: Switching Time Test Circuit

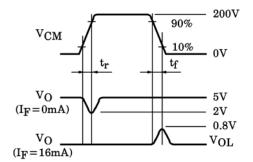




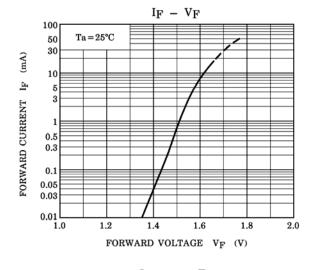
Test Circuit 2: Common Mode Noise Immunity Test Circuit

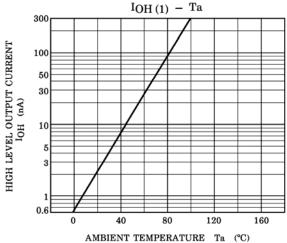


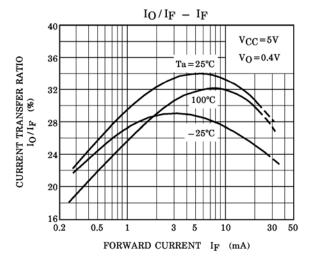
$$\text{CM}_{H}\!=\frac{160\,(\text{V})}{t_{\text{T}}\,(\mu\text{s})}$$
 , $\text{CM}_{L}\!=\frac{160\,(\text{V})}{t_{\text{f}}\,(\mu\text{s})}$

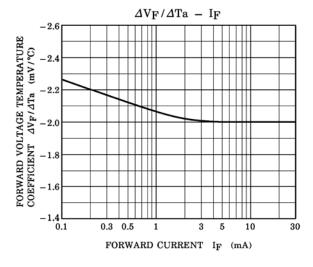


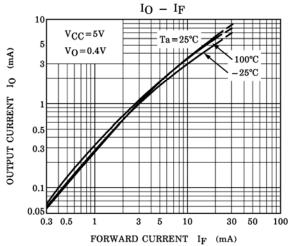
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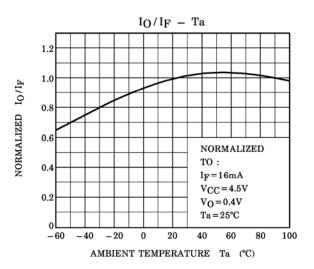




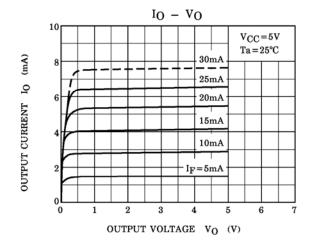


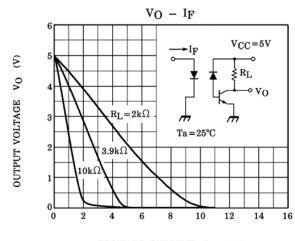


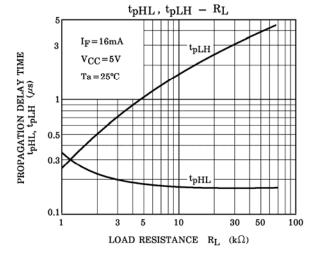




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